

8 AMP SILICON BRIDGE RECTIFIERS

ACTUAL SIZE

FEATURES

- VOID FREE VACUUM DIE SOLDERING FOR MAXIMUM MECHANICAL STRENGTH AND HEAT DISSIPATION (Solder Voids: Typical < 2%, Max. < 10% of Die Area)
- **BUILT-IN STRESS RELIEF MECHANISM FOR** • SUPERIOR RELIABILITY AND PERFORMANCE
- SURGE OVERLOAD RATING TO 300 AMPS PEAK

RECOGNIZED - FILE #E124962

MECHANICAL DATA

- Case: Molded plastic, U/L Flammability Rating 94V-0 •
- Terminals: Round silver plated copper pins •
- Soldering: Per MIL-STD 202 Method 208 guaranteed •
- · Polarity: Marked on side of case; positive lead at beveled corner
- Mounting Position: Any. Through hole provided for #6 screw •
- Weight: 0.18 Ounces (5.4 Grams)

MECHANICAL SPECIFICATION



| SYM | MILLIM | IETERS | INCHES | | | | | | |
|-----|--------|--------|--------|-------|--|--|--|--|--|
| | MIN | MAX | MIN | MAX | | | | | |
| BL | 18.5 | 19.6 | 0.73 | 0.77 | | | | | |
| BH | 6.4 | 7.6 | 0.25 | 0.3 | | | | | |
| D1 | 12.2 | 13.2 | 0.48 | 0.52 | | | | | |
| LL | 22.2 | n/a | 0.875 | n/a | | | | | |
| LD | 1.2 | 1.3 | 0.048 | 0.052 | | | | | |



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MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load.

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|--|----------|------------------|------------|------------|-----------|-----------|-----------------------------|-----------|-----------|-----------|--------------------------|-------|
| PARAMETER (TEST CONDITIONS) | | RATINGS | | | | | | | | | | |
| | | | | LED CHE | | N | ION-CONTROLLED AVALANCHE | | | | | UNITS |
| Series Number | | ADB 804 | ADB 806 | ADB 808 | DB 800 | DB 801 | DB 802 | DB 804 | DB 806 | DB 808 | DB 810 | |
| Maximum DC Blocking Voltage | Vrm | | | | | | | | | | | |
| Working Peak Reverse Voltage | Vrwm | 400 | 600 | 800 | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | VOLTS |
| Maximum Peak Recurrent Reverse Voltage | Vrrm | | | | | | | | | | | |
| RMS Reverse Voltage | VR (RMS) | 280 | 420 | 560 | 35 | 70 | 140 | 280 | 420 | 560 | 700 | |
| Power Dissipation in V(BR) Region for 100 μ S Square Wave | Ргм | 400 | | n/a | | | | | | | | |
| Continuous Power Dissipation in V(BR) Region @ THs=80° C (Heat Sink Temp) | Pr | 2 | | | n/a | | | | | | | WATTS |
| Thermal Energy (Rating for Fusing) | l²t | 64 | | | | | | | | | AMPS ² SEC | |
| Peak Forward Surge Current. Single 60Hz Half-Sine Wave Superimposed on Rated Load (JEDEC Method). TJ = 150° C | | 300 | | | | | | | | AMPS | | |
| Average Forward Rectified Current@ Tc = 50° C (Note 1)@ Ta = 50° C (Note 2) | lo | 10 8 | | | | | | | | | | |
| Junction Operating and Storage Temperature Range | | -55 to +150 | | | | | | | | | °C | |
| Minimum Avalanche Voltage | | See Note 4 | | n/a | | | | | | | | |
| Maximum Avalanche Voltage | | See Note 4 | | n/a | | | | | | | VOLTS | |
| Maximum Forward Voltage (Per Diode) at 4 Amps DC | | 0.95 (Typ. 0.90) | | | | | | | | | | |
| Maximum Reverse Current at Rated VRM $@$ Ta = 25° C $@$ Ta = 125° C | | 1 50 | | | | | | | | μΑ | | |
| Minimum Insulation Breakdown Voltage (Circuit to Case) | | 2000 | | | | | | | | VOLTS | | |
| Typical Thermal Resistance Junction to Ambient (Note 2) Junction to Case (Note 1) | | 12 5 | | | | | | | | | °C/W | |

NOTES: (1) Bridge mounted on 4.9" x 4.3" x 0.11" thick (12.4cm x 10.8cm x 0.3cm) aluminum plate

(2) Bridge mounted on PC Board with 0.5" sq. (12mm sq.) copper pads and bridge lead length of 0.375" (9.5mm)
(3) Bolt bridge on heat sink, using silicon thermal compound between bridge and mounting surface, for maximum heat transfer
(4) These bridges exhibit the avalanche characteristic at breakdown. If your application requires a specific breakdown voltage range, please contact us.



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RATING & CHARACTERISTIC CURVES FOR SERIES DB800 - DB810 and SERIES ADB804 - ADB808



FIGURE 1. FORWARD CURRENT DERATING CURVE









FIGURE 2. MAXIMUM NON-REPETITIVE SURGE CURRENT



Percent of Rated Peak Reverse Voltage FIGURE 4. TYPICAL REVERSE CHARACTERISTICS

NOTES

(1) Case Temperature, Tc, With Bridge Mounted on 4.9" x 4.3" x 0.11" Thick (12.4cm x 10.8cm x 0.3cm) Aluminum Plate

Ambient Temperature, TA, With Bridge Mounted on PC Board With 0.5" Sq. (12mm Sq.) Copper Pads And Bridge Lead Length of 0.375" (9.5mm)

(2) TJ = 150° C

(3) TJ = 25°C; Pulse Width = 300 μ Sec; 1% Duty Cycle

(4) TJ = 25°C; f = 1 MHz; Vsig = 50mVp-p